

HSF

NOTES:

Current Rating: 1.5AMP
 Contact Resistance: 20mΩ Max
 Withstand Voltage: 500V AC/DC
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40℃ to +105℃

Contact Material: Copper Alloy
 Contact Plating: Au Over Ni
 Insulator Material: High Temperature
 Thermoplastic(UL94V-0)

Ordering Information

2293P-4 XX S XX C Y N X 2

No. of Pins per ROW: 02-40PIN

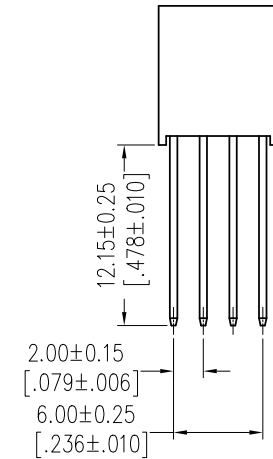
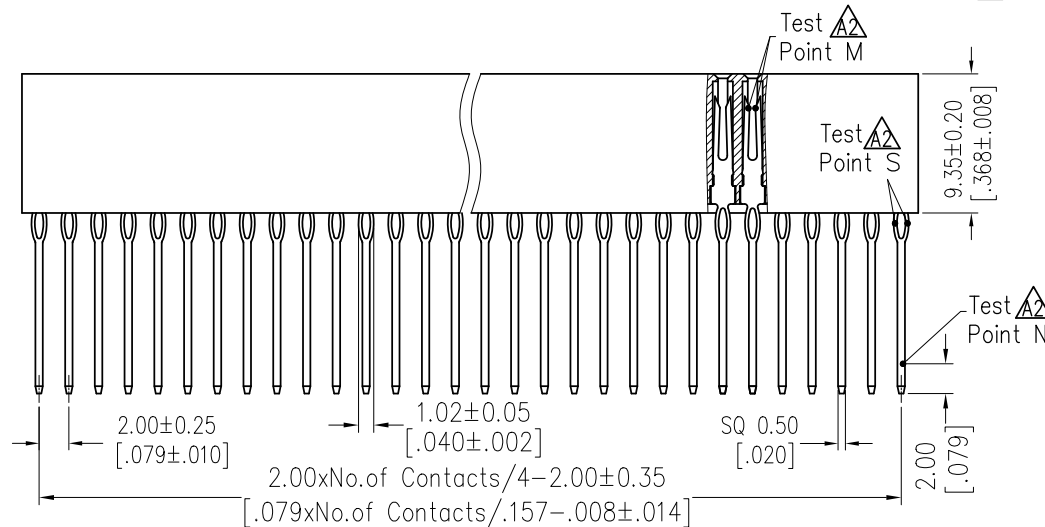
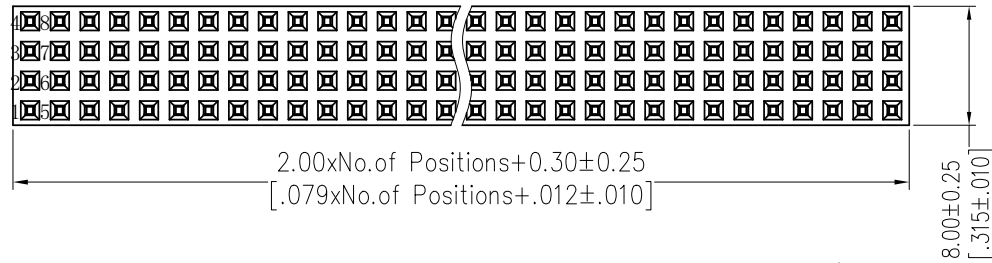
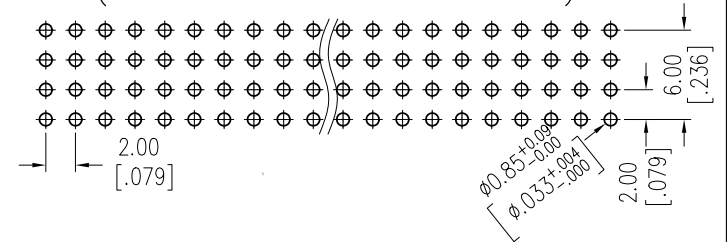
Contact Plating:
 G1=Fully 3μ"Gold
 G3=Fully 10μ"Gold
 G4=Fully 15μ"Gold
 H3=Mating 10μ"Gold
 Tail 3μ"Gold
 H4=Mating 15μ"Gold
 Tail 3μ"Gold

Packing:
 T=Tube

Contact Plating	Test Point M	Test Point N	Test Point S
G1	3U"	3U"	3U"
G3	10U"	10U"	3U"
G4	15U"	15U"	3U"
H3	10U"	3U"	3U"
H4	15U"	3U"	3U"

Item	Pitch	Mating
Standard	2.00	1215/1220
Alternate		

Recommended P.C.B Layout(Top Side)
 (PCB BOARD TOLERANCE±0.05)



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW XSR	DATE	SCALE	FIT	PART NO.
A2	2019/12/30	Modify drawing	-----	x.x ±0.40	CHECK	2019/12/30	UNIT	mm	2293P-4XXSXXCYNX2
A1	2014/02/09	Modify drawing	-----	x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE: 2.0*2.0mm PC104 Plus FOUR ROW 180°DIP H=9.35 PRESS FIT
A0	2012/07/28	NEW	-----	x.xxx ±0.15	APPROVE	DATE	SHEET	1/1	Customer NO.
				Angle ± 3°			PROJ.		
				DIM TOL					